JMTM8205A

Description

JMT Dual N-channel Enhancement Mode Power MosFET

Features

• 19.5V, 5A

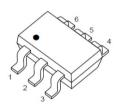
 $R_{DS(ON)} < 24.1 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$ $R_{DS(ON)} < 29.6 \text{m}\Omega$ @ $V_{GS} = 2.5 \text{V}$

- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free

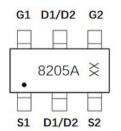
Applicatio

- Load Switch
- PWM Application
- Power Management

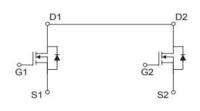








Marking and Pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
8205A	JMTM8205A	TAPING	SOT-23-6L	7"	3000	120000

Absolute Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V _{DS}	Drain-to-Source Voltage		19.5	V
V_{GS}	Gate-to-Source Voltage		±12	V
	Continuous Drain Current	T _A = 25°C	5	^
I _D	Continuous Diain Current	T _A = 100°C	3	A
I _{DM}	Pulsed Drain Current (1)		20	Α
P_{D}	Power Dissipation	T _A = 25°C	1.8	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾		68	°C/W
T_J , T_{STG}	Junction & Storage Temperature R	ange	-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	19.5	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 19V, V _{GS} = 0V	-	-	1.0	μА
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	-	-	±100	nA
On Cha	aracteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	0.7	1.0	V
Б	Ct 1: D : C	$V_{GS} = 4.5V, I_D = 4A$	-	18.5	24.1	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 2.5V, I_D = 3A$	-	22.8	29.6	mΩ
Dynam	ic Characteristics					
C _{iss}	Input Capacitance		-	447	-	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 10V,$	-	64	-	pF
C_{rss}	Reverse Transfer Capacitance	f = 1MHz	-	52	-	pF
Q_g	Total Gate Charge		-	5.2	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 4.5V$ $V_{DS} = 10V, I_D = 3A$	-	0.9	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 10V, I _D - 3A	-	1.1	-	nC
Switch	ing Characteristics					
$t_{d(on)}$	Turn-On DelayTime		-	4	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 4.5V, V_{DD} = 10V$	1	28	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 3A$, $R_{GEN} = 3\Omega$	1	66	-	ns
t_{f}	Turn-Off Fall Time		-	50	-	ns
Drain-S	Source Diode Characteristics and M	ax Ratings				
Is	Maximum Continuous Drain to Source Diode	Forward Current	-	-	5	А
I _{SM}	Maximum Pulsed Drain to Source Diode For	ward Current	-	-	20	Α
V_{SD}	Drain to Source Diode ForwardVoltage	$V_{GS} = 0V, I_{S} = 5A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 50 - 4000	-	4.7	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 5A$, di/dt = 100A/us	-	0.8	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB



Typical Performance Characteristics

Figure 1: Output Characteristics

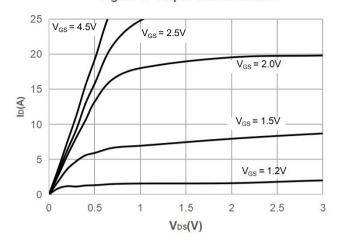


Figure 2: Typical Transfer Characteristics

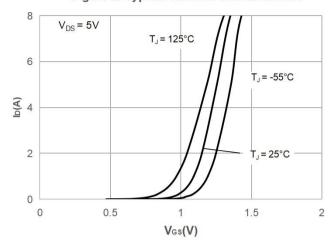


Figure 3: On-resistance vs. Drain Current

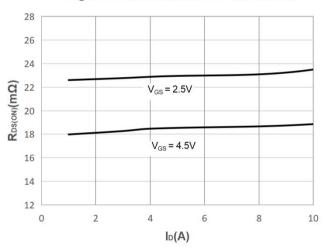


Figure 4: Body Diode Characteristics

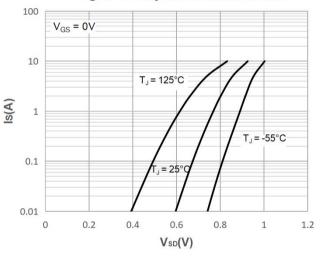


Figure 5: Gate Charge Characteristics

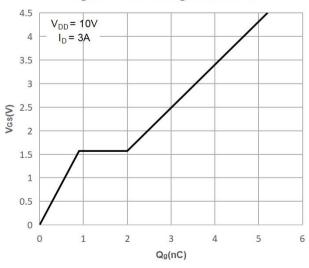
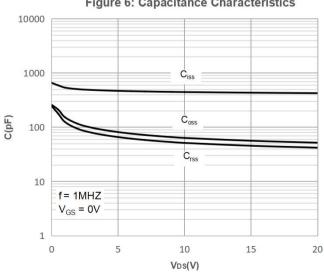


Figure 6: Capacitance Characteristics





Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs.
Junction Temperature

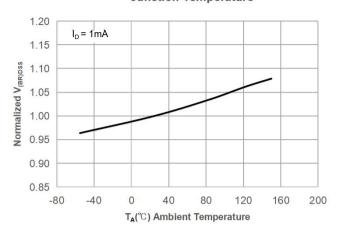


Figure 9: Maximum Safe Operating Area

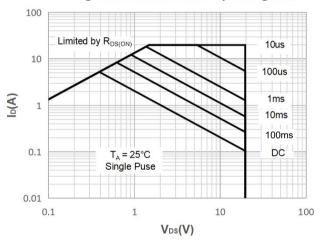


Figure 11: Normalized Maximum Transient
Thermal Impedance

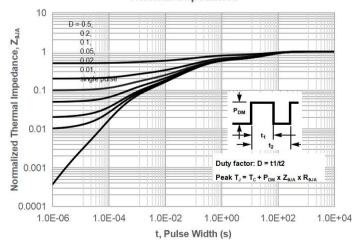


Figure 8: Normalized on Resistance vs. Junction Temperature

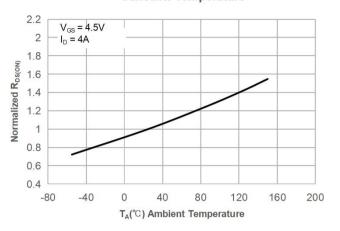


Figure 10: Maximum Continuous Drian Current vs. Ambient Temperature

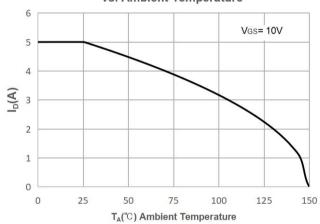
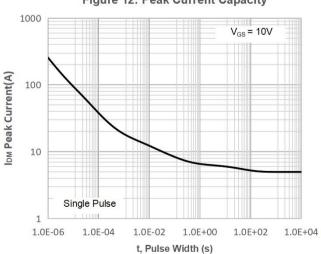


Figure 12: Peak Current Capacity





Test Circuit

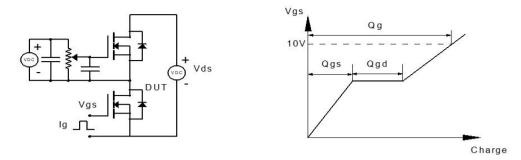


Figure 1: Gate Charge Test Circuit & Waveform

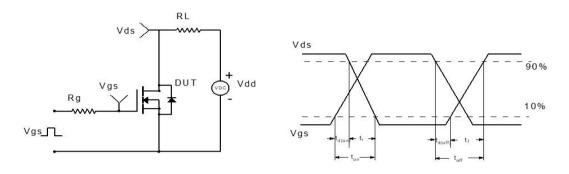


Figure 2: Resistive Switching Test Circuit & Waveform

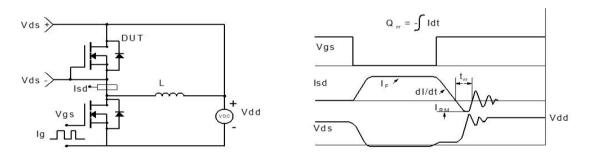
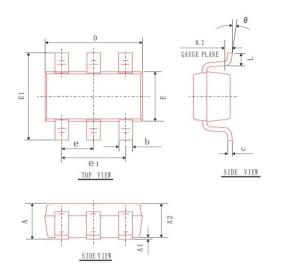


Figure 3: Diode Recovery Test Circuit & Waveform

JMTM8205A

Package Mechanical Data(SOT-23-6L)



COMMON DIMENSIONS (UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX	
A			1.20	
A 1	0.00	0.05	0.10	
A2	1.00	1.10	1.20	
b	0.30	0.40	0.50	
C	0.119	0.127	0.135	
e 1	1.80	1.90	2.00	
D	2.80	2.90	3.00	
Е	1.50	1.60	1.70	
E1	2.60	2. 80	3.00	
L	0.30	0.45	0.60	
θ	0°	4°	8°	
e	0. 95BSC			

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